ABSTRACT

METHOD OF FORMING LOW WIRE LOOPS AND WIRE LOOPS FORMED USING THE METHOD

The invention provides a method of bonding wire between first and second bonding points with a bonding tool, such as a capillary. It comprises the steps of forming a first bond at the first bonding point with the bonding tool, moving the bonding tool away from the first bond by a first distance, then moving the bonding tool towards the first bonding point and coupling the wire to the first bond. Thereafter, the bonding tool is moved away from the first bond by a second distance and a kink is formed in the wire. The bonding tool is subsequently moved to extend a sufficient length of wire to form a wire loop between the first and second bonding points before the bonding tool is moved to the second bonding point to form a second bond. Characteristics of wire bonds formable using the method of the invention are also disclosed.

(Figure 2(a))